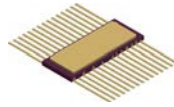


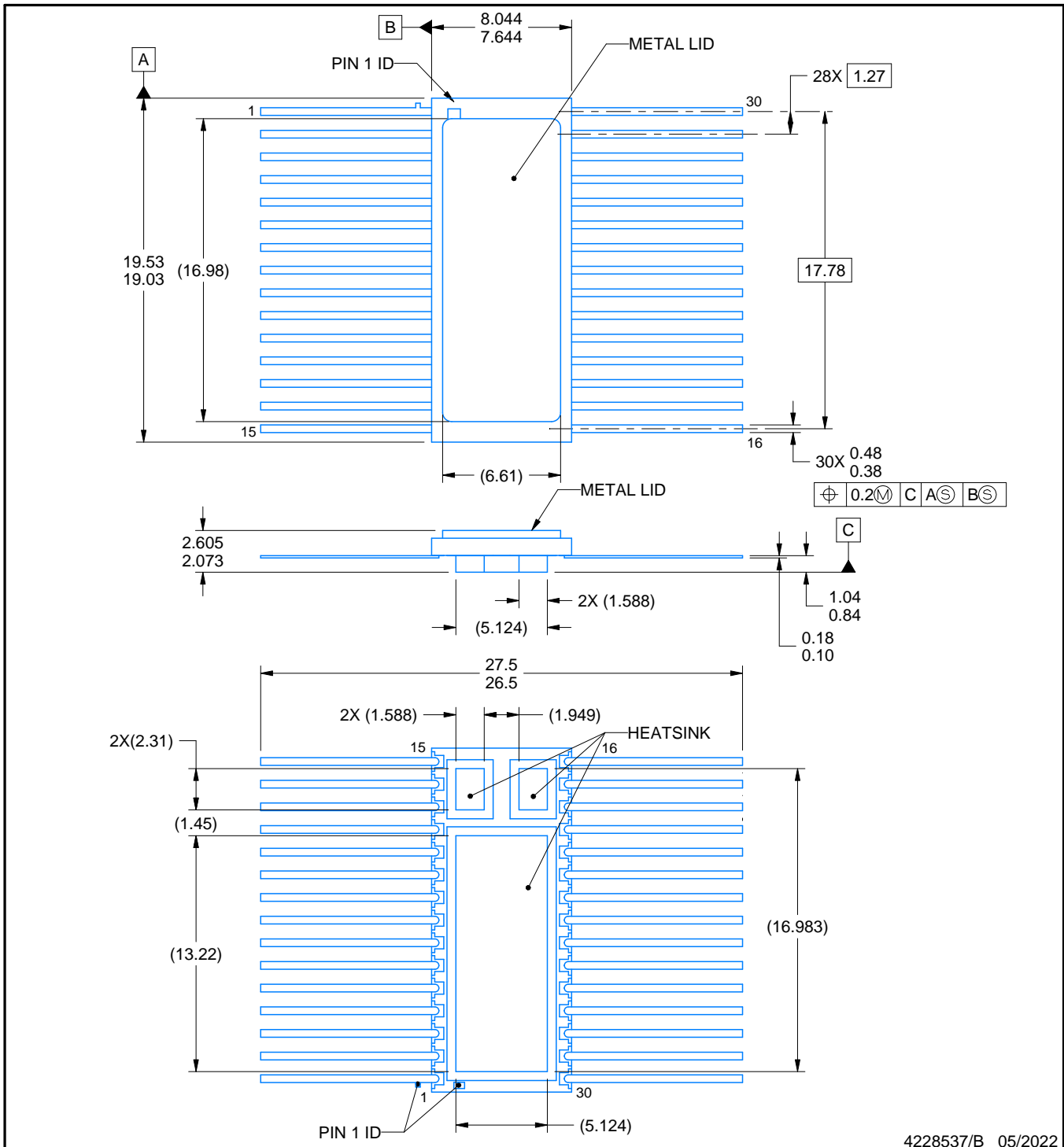
HLB0030A



PACKAGE OUTLINE

CFP - 2.605 mm max height

CERAMIC DUAL FLATPACK



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NOTES:

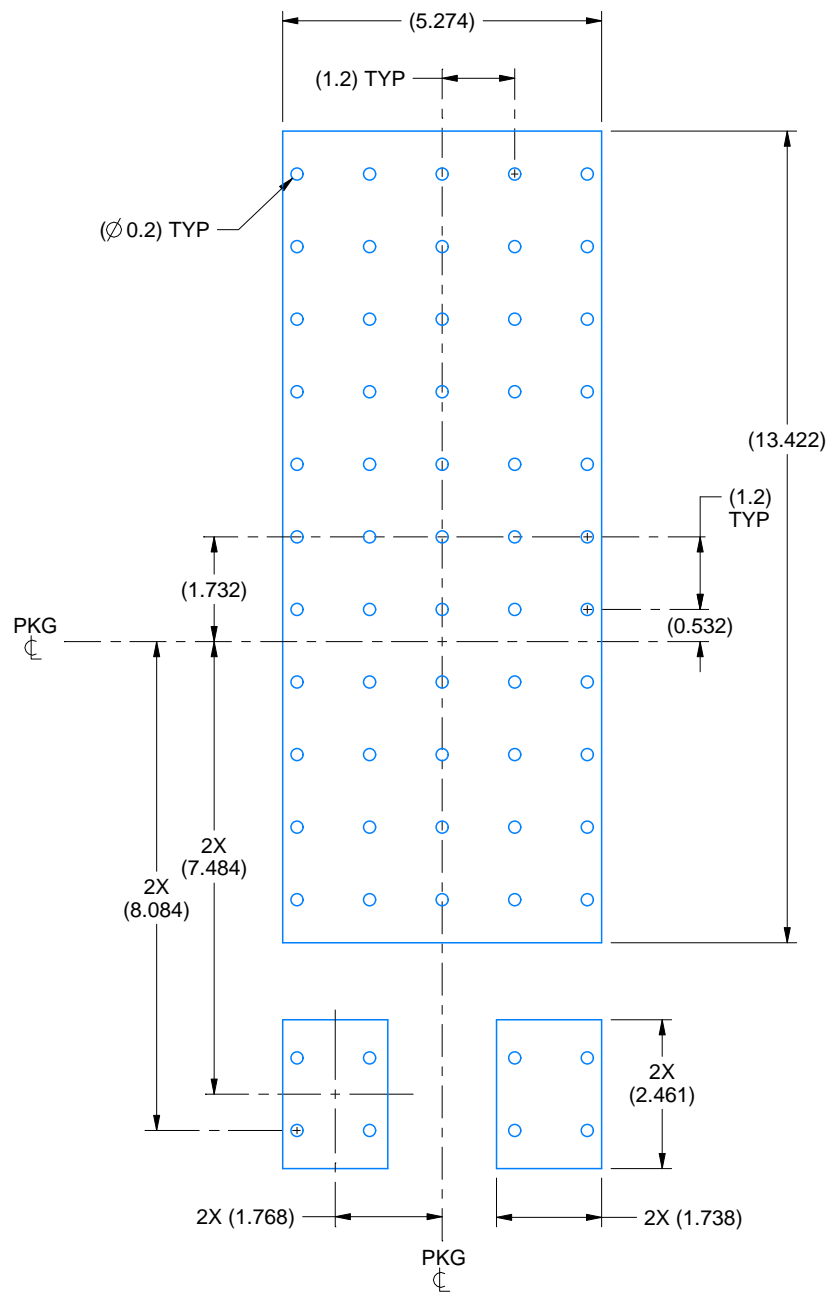
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This package is hermetically sealed with a metal lid.
4. The terminals are gold plated.
5. Falls within MIL-STD-1835 CDFP-F11A.

EXAMPLE BOARD LAYOUT

HLB0030A

CFP - 2.605 mm max height

CERAMIC DUAL FLATPACK



HEATSINK LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:8X

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